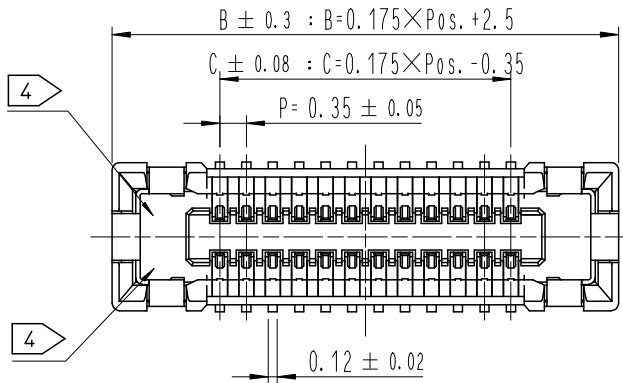


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please contact a company representative for further information.

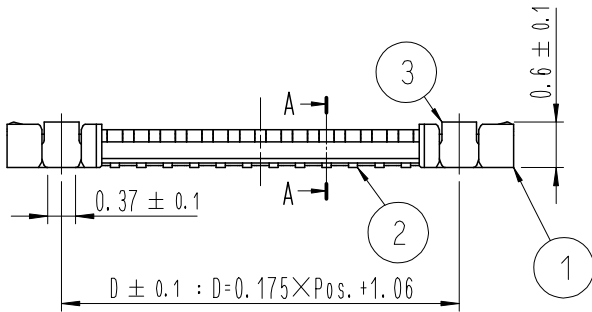
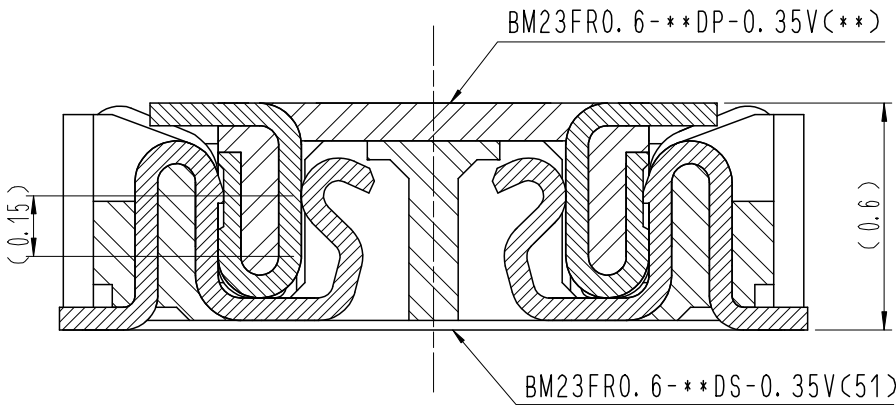
1 2 3 4 5 6 7 8

	COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE		COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE
△	4	RE-6-0649	J.S.H	J.H.W		16. 05. 04	△						
△	3	RE-6-0774	J.S.H	J.H.W		16. 11. 07	△						
△							△						

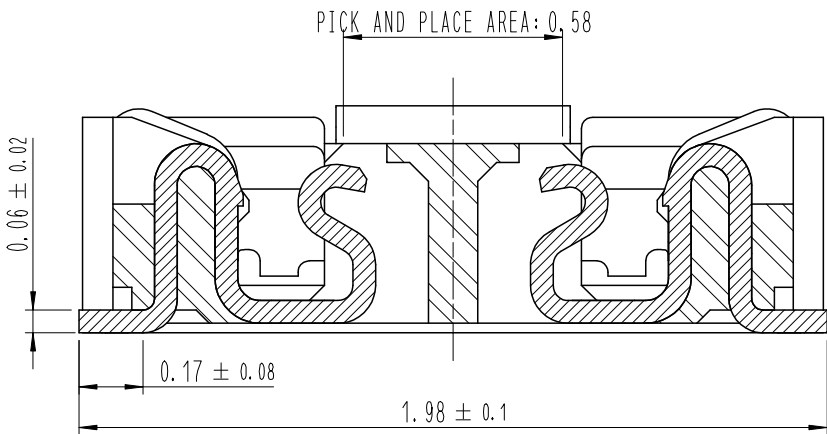


DRAWING FOR REFERENCE
This is subject to change without notice

ENGAGEMENT FIGURE (50:1)



A-A (50:1)



△ PART No.	CODE No.	POS.	B	C	D
BM23FR0.6-6DS-0.35V(51)	-	6	3.55	0.70	2.11
BM23FR0.6-8DS-0.35V(51)	-	8	3.90	1.05	2.46
BM23FR0.6-10DS-0.35V(51)	-	10	4.25	1.40	2.81
BM23FR0.6-12DS-0.35V(51)	-	12	4.60	1.75	3.16
BM23FR0.6-16DS-0.35V(51)	-	16	5.30	2.45	3.86
BM23FR0.6-20DS-0.35V(51)	-	20	6.00	3.15	4.56
BM23FR0.6-24DS-0.35V(51)	-	24	6.70	3.85	5.26
BM23FR0.6-30DS-0.35V(51)	-	30	7.75	4.90	6.31
BM23FR0.6-34DS-0.35V(51)	-	34	8.45	5.60	7.01
BM23FR0.6-40DS-0.35V(51)	-	40	9.50	6.65	8.06
BM23FR0.6-50DS-0.35V(51)	-	50	11.25	8.40	9.81

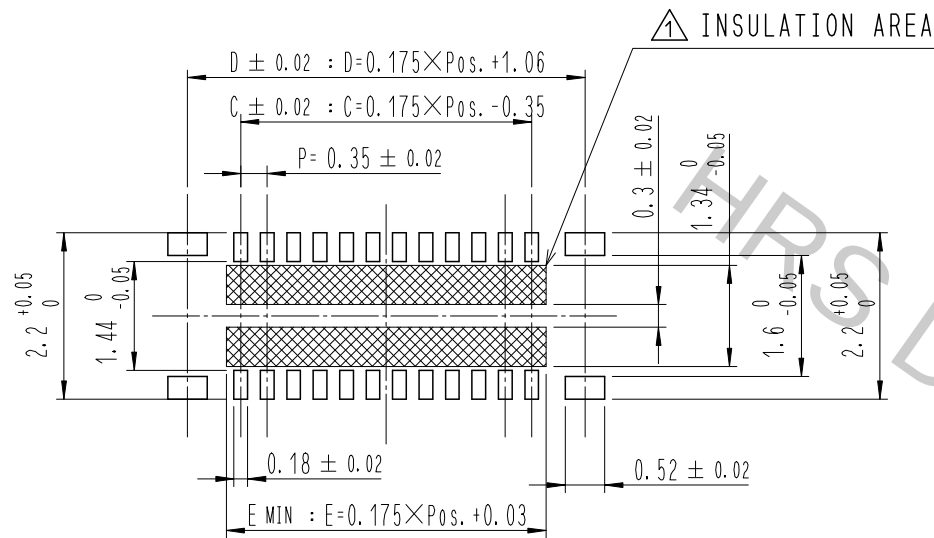
- NOTE
- 1. ALL LEAD CO-PLANARITY SHALL BE 0.1mm MAX.
 - 2. CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD 0.05 μ m MIN
SMT LEAD : GOLD 0.05 μ m MIN
UNDERPLATING : NICKEL 1 μ m MIN
(SURFACE : SEALING)
 - 3. MATA L FITTING PLATING SPECIFICATIONS
SMT LEAD : GOLD 0.05 μ m MIN
UNDERPLATING : NICKEL 1 μ m MIN
(SURFACE : SEALING)
 - 4. HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.

4	PS	CLEAR (EMBOSSED CARRIER TAPE)			
3	PHOSPHOR BRONZE	3	7	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2	6	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
REMARKS			DRAWN	DESIGNED	CHECKED
			D. W. KIM	D. W. KIM	H. W. JO
			14.11.06	14.11.06	14.11.06
			APPROVED	RELEASED	
			T. S. KANG	16.11.07	
CODE NO. (OLD)			DRAWING NO. EDC3-*****		
SCALE 10:1			PART NO. BM23FR0.6-**-DS-0.35V(51)		
UNITS mm			CODE NO CL 66**-*****-***		
			1/3		

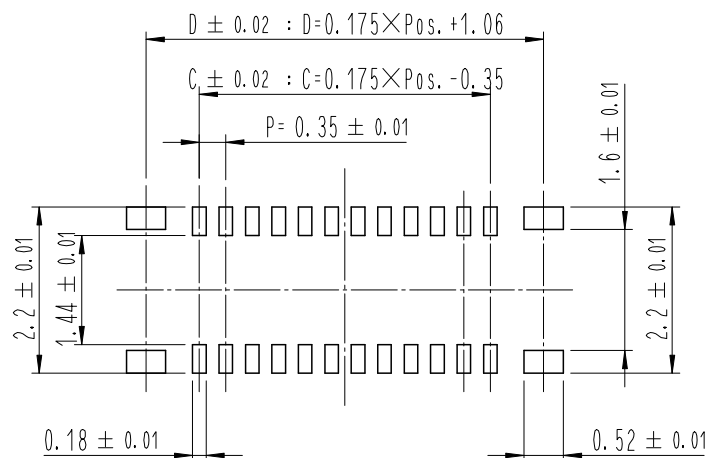
1 2 3 4 5 6 7 8

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6 RECOMMENDED PCB LAYOUT

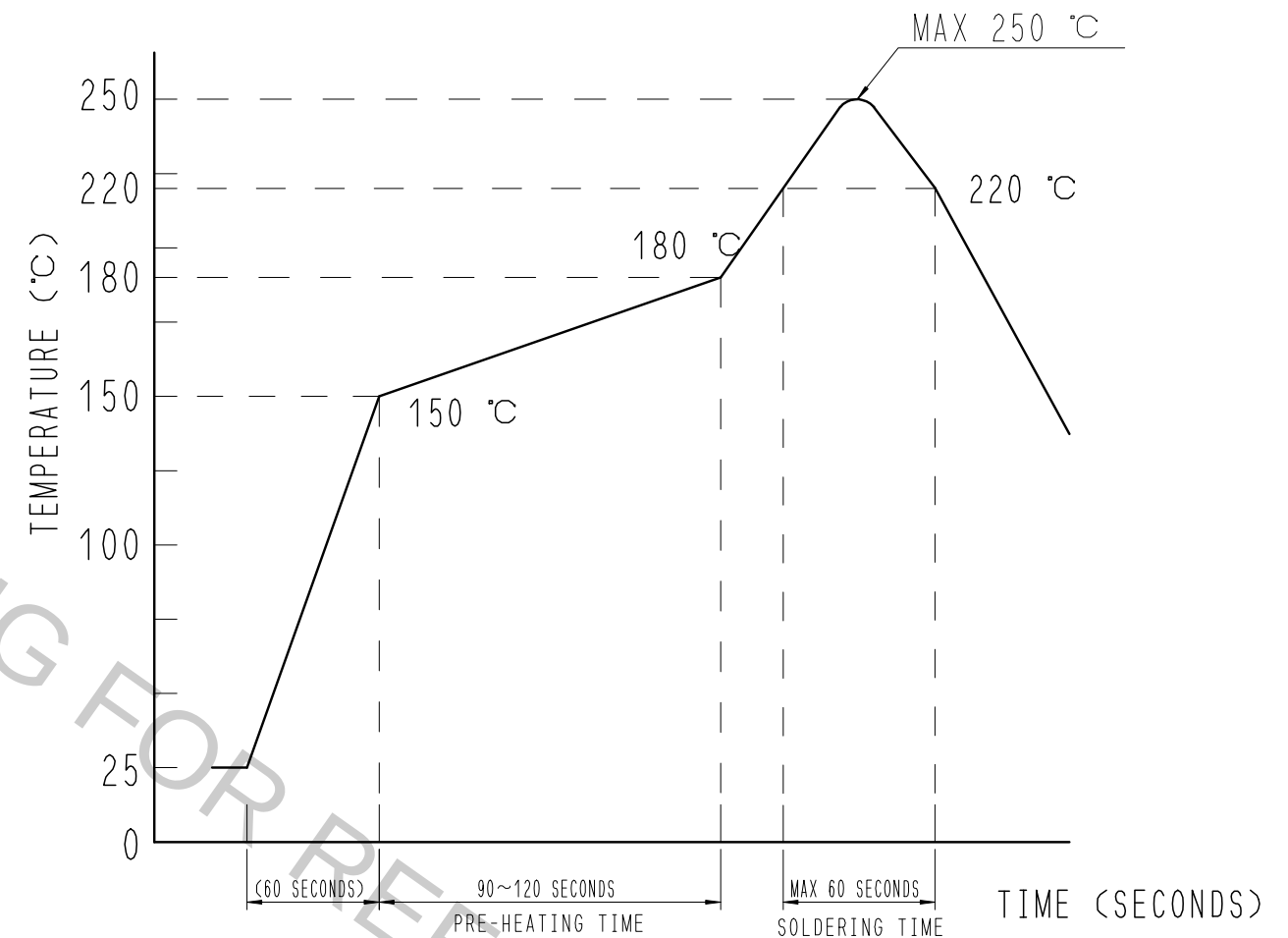


RECOMMENDED METAL MASK DIMENSIONS
METAL MASK THICKNESS : $100 \mu\text{m}$



△ POS.	C	D	E
6	0.70	2.11	1.08
8	1.05	2.46	1.43
10	1.40	2.81	1.78
12	1.75	3.16	2.13
16	2.45	3.86	2.83
20	3.15	4.56	3.53
24	3.85	5.26	4.23
30	4.90	6.31	5.28
34	5.60	7.01	5.98
40	6.65	8.06	7.03
50	8.40	9.81	8.78

5 RECOMMENDED REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
1) REFLOW TIME
DURATION ABOVE 220 °C: 60 SEC MAX.
(PEAK TEMPERATURE: 250 °C MAX)
2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE (MIN): 150 °C
PRE-HEAT TEMPERATURE (MAX): 180 °C
PRE-HEAT TIME: 90-120 SEC.

- 5 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
- 6 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-*****	PART NO.	BM23FR0.6-**DS-0.35V(51)
	SCALE	10:1	CODE NO	CL 66**-*****-***
	UNITS	mm		

